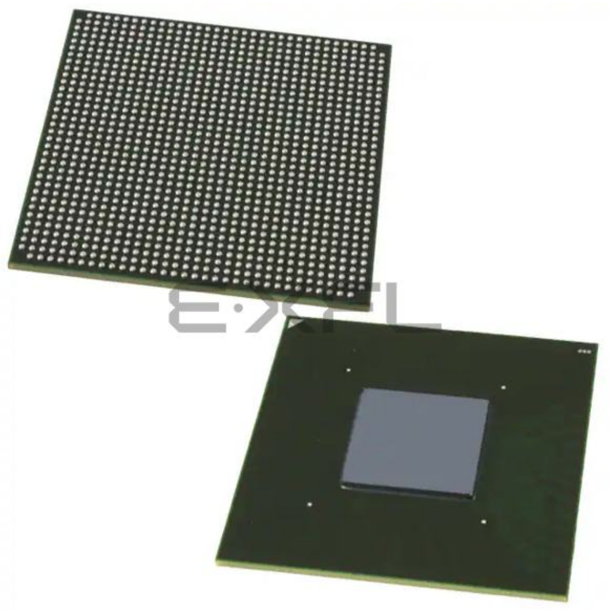

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	23780
Number of Logic Elements/Cells	504000
Total RAM Bits	27695104
Number of I/O	544
Number of Gates	-
Voltage - Supply	1.12V ~ 1.18V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA Exposed Pad
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agtfd7h3f35i3n

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Arria V GZ Device Datasheet........ 2-1
Electrical Characteristics........ 2-1

Symbol	Description	Minimum[5]	Typical	Maximum[5]	Unit
V_{CCL_GXBL}	GX and SX speed grades—clock network power (left side)	1.08/1.12	1.1/1.15[6]	1.14/1.18	V
V_{CCL_GXBR}	GX and SX speed grades—clock network power (right side)				
V_{CCL_GXBL}	GT and ST speed grades—clock network power (left side)	1.17	1.20	1.23	V
V_{CCL_GXBR}	GT and ST speed grades—clock network power (right side)				

Related Information

Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines

Provides more information about the power supply connection for different data rates.

HPS Power Supply Operating Conditions

Table 1-5: HPS Power Supply Operating Conditions for Arria V SX and ST Devices

This table lists the steady-state voltage and current values expected from Arria V system-on-a-chip (SoC) devices with ARM®-based hard processor system (HPS). Power supply ramps must all be strictly monotonic, without plateaus. Refer to Recommended Operating Conditions for Arria V Devices table for the steady-state voltage values expected from the FPGA portion of the Arria V SoC devices.

Symbol	Description	Condition	Minimum[7]	Typical	Maximum[7]	Unit
V_{CC_HPS}	HPS core voltage and periphery circuitry power supply	–C4, –I5, –C5, –C6	1.07	1.1	1.13	V
		–I3	1.12	1.15	1.18	V

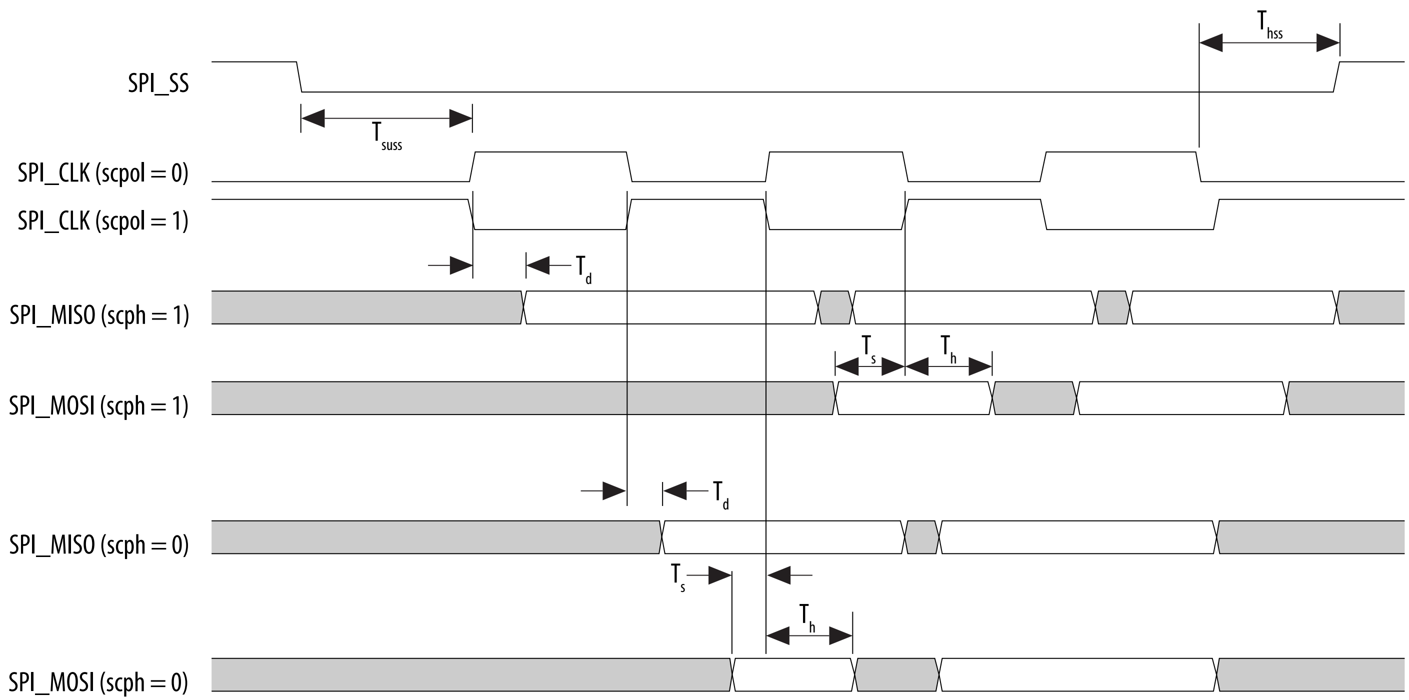
(5) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

(7) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Symbol	Description	Min	Max	Unit
T_h	SPI MISO hold time	1	—	ns
$T_{dutycycle}$	SPI_CLK duty cycle	45	55	%
$T_{dssfrst}$	Output delay SPI_SS valid before first clock edge	8	—	ns
T_{dsslst}	Output delay SPI_SS valid after last clock edge	8	—	ns
T_{dio}	Master-out slave-in (MOSI) output delay	–1	1	ns

(86) This value is based on `rx_sample_dly` = 1 and `spi_m_clk` = 120 MHz. `spi_m_clk` is the internal clock that is used by SPI Master to derive it's `SCLK_OUT`. These timings are based on `rx_sample_dly` of 1. This delay can be adjusted as needed to accommodate slower response times from the slave. Note that a delay of 0 is not allowed. The setup time can be used as a reference starting point. It is very crucial to do a calibration to get the correct `rx_sample_dly` value because each SPI slave device may have different output delay and each application board may have different path delay. For more information about `rx_sample_delay`, refer to the SPI Controller chapter in the Hard Processor System Technical Reference Manual.

Figure 1-10: SPI Slave Timing Diagram



Related Information

SPI Controller, Arria V Hard Processor System Technical Reference Manual

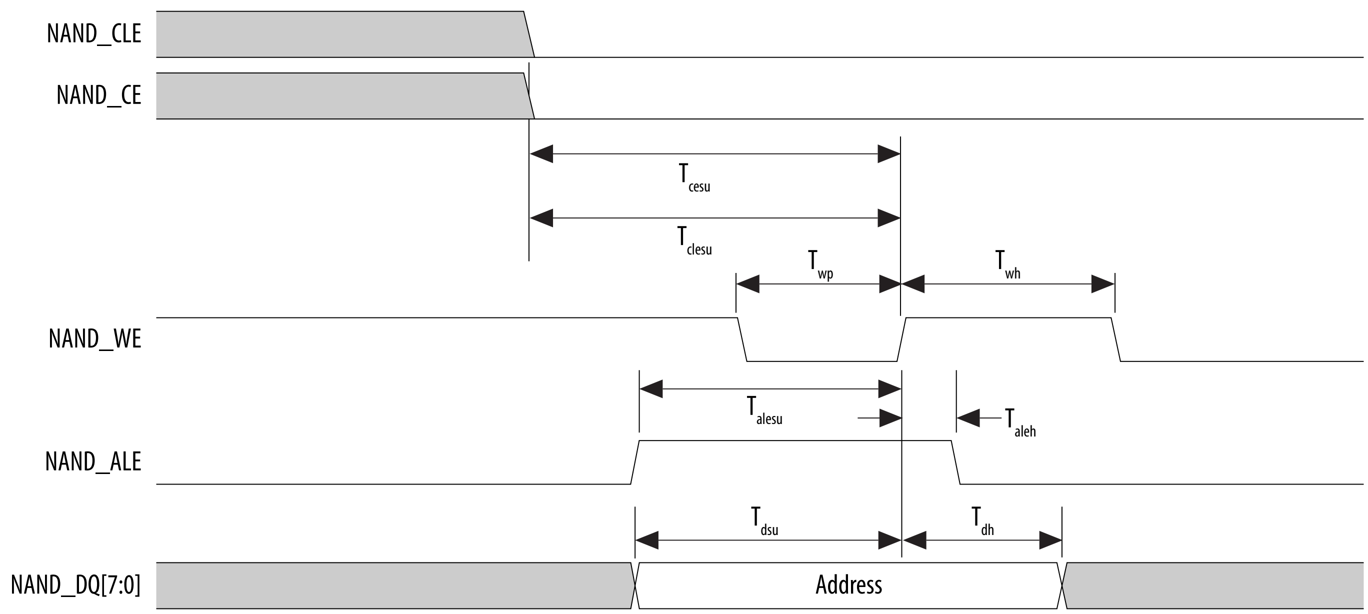
Provides more information about rx_sample_delay.

SD/MMC Timing Characteristics

Table 1-54: Secure Digital (SD)/MultiMediaCard (MMC) Timing Requirements for Arria V Devices

After power up or cold reset, the Boot ROM uses `drvsel` = 3 and `smplsel` = 0 to execute the code. At the same time, the SD/MMC controller enters the Identification Phase followed by the Data Phase. During this time, the value of interface output clock `SDMMC_CLK_OUT` changes from a maximum of 400 kHz (Identification Phase) up to a maximum of 12.5 MHz (Data Phase), depending on the internal reference clock `SDMMC_CLK` and the `CSEL` setting. The value of `SDMMC_CLK` is based on the external oscillator frequency and has a maximum value of 50 MHz.

Figure 1-18: NAND Address Latch Timing Diagram



POR Delay	Minimum	Maximum	Unit
Standard	100	300	ms

Related Information

MSEL Pin Settings

Provides more information about POR delay based on MSEL pin settings for each configuration scheme.

FPGA JTAG Configuration Timing

Table 1-64: FPGA JTAG Timing Parameters and Values for Arria V Devices

Symbol	Description	Min	Max	Unit
t_{JCP}	TCK clock period	30, 167(92)	—	ns
t_{JCH}	TCK clock high time	14	—	ns
t_{JCL}	TCK clock low time	14	—	ns
$t_{JPSU (TDI)}$	TDI JTAG port setup time	2	—	ns
$t_{JPSU (TMS)}$	TMS JTAG port setup time	3	—	ns
t_{JPH}	JTAG port hold time	5	—	ns
t_{JPCO}	JTAG port clock to output	—	12(93)	ns
t_{JPZX}	JTAG port high impedance to valid output	—	14(93)	ns
t_{JPXZ}	JTAG port valid output to high impedance	—	14(93)	ns

(92) The minimum TCK clock period is 167 ns if V_{CCBAT} is within the range 1.2 V – 1.5 V when you perform the volatile key programming.

(93) A 1-ns adder is required for each VCCIO voltage step down from 3.0 V. For example, tJPCO= 13 ns if VCCIO of the TDO I/O bank = 2.5 V, or 14 ns if it equals 1.8 V.

Date	Version	Changes

January 2015	2015.01.30	• Updated the description for $V_{CC\_AUX\_SHARED}$ to “HPS auxiliary power supply” in the following tables:
		  • Absolute Maximum Ratings for Arria V Devices
		  • HPS Power Supply Operating Conditions for Arria V SX and ST Devices
		• Added statement in I/O Standard Specifications: You must perform timing closure analysis to determine the maximum achievable frequency for general purpose I/O standards.
		• Updated the conditions for transceiver reference clock rise time and fall time: Measure at ±60 mV of differential signal. Added a note to the conditions: `REFCLK` performance requires to meet transmitter `REFCLK` phase noise specification.
		• Updated the description in Periphery Performance Specifications to mention that proper timing closure is required in design.
		• Updated HPS Clock Performance main_base_clk specifications from 525 MHz (for –I3 speed grade) and 462 MHz (for –C4 speed grade) to 400 MHz.
		• Updated HPS PLL VCO maximum frequency to 1,600 MHz (for –C5, –I5, and –C6 speed grades), 1,850 MHz (for –C4 speed grade), and 2,100 MHz (for –I3 speed grade).
		• Changed the symbol for HPS PLL input jitter divide value from NR to N.
		• Removed “Slave select pulse width (Texas Instruments SSP mode)” parameter from the following tables:
		  • SPI Master Timing Requirements for Arria V Devices
		  • SPI Slave Timing Requirements for Arria V Devices
		• Added descriptions to USB Timing Characteristics section in HPS Specifications: PHYs that support LPM mode may not function properly with the USB controller due to a timing issue. It is recommended that designers use the MicroChip USB3300 PHY device that has been proven to be successful on the development board.
		• Added HPS JTAG timing specifications.
		• Updated FPGA JTAG timing specifications note as follows: A 1-ns adder is required for each V_{CCIO} voltage step down from 3.0 V. For example, t_{JPCO} = 13 ns if V_{CCIO} of the TDO I/O bank = 2.5 V, or 14 ns if it equals 1.8 V.
		• Updated the value in the V_{ICM} (AC Coupled) row and in note 6 from 650 mV to 750 mV in the Transceiver Specifications for Arria V GT and ST Devices table.

Symbol	Description	Minimum	Maximum	Unit
V_I	DC input voltage	–0.5	3.8	V
T_J	Operating junction temperature	–55	125	°C
T_{STG}	Storage temperature (No bias)	–65	150	°C
I_{OUT}	DC output current per pin	–25	40	mA

Table 2-3: Transceiver Power Supply Absolute Conditions for Arria V GZ Devices

Symbol	Description	Minimum	Maximum	Unit
V_{CCA_GXBL}	Transceiver channel PLL power supply (left side)	–0.5	3.75	V
V_{CCA_GXBR}	Transceiver channel PLL power supply (right side)	–0.5	3.75	V
V_{CCHIP_L}	Transceiver hard IP power supply (left side)	–0.5	1.35	V
V_{CCHSSI_L}	Transceiver PCS power supply (left side)	–0.5	1.35	V
V_{CCHSSI_R}	Transceiver PCS power supply (right side)	–0.5	1.35	V
V_{CCR_GXBL}	Receiver analog power supply (left side)	–0.5	1.35	V
V_{CCR_GXBR}	Receiver analog power supply (right side)	–0.5	1.35	V
V_{CCT_GXBL}	Transmitter analog power supply (left side)	–0.5	1.35	V
V_{CCT_GXBR}	Transmitter analog power supply (right side)	–0.5	1.35	V
V_{CCH_GXBL}	Transmitter output buffer power supply (left side)	–0.5	1.8	V
V_{CCH_GXBR}	Transmitter output buffer power supply (right side)	–0.5	1.8	V

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage shown in the following table. They may also undershoot to –2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

Bus Hold Specifications

Table 2-9: Bus Hold Parameters for Arria V GZ Devices

Parameter	Symbol	Conditions	V_{CCIO}										Unit
			1.2 V		1.5 V		1.8 V		2.5 V		3.0 V		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Low sustaining current	I_{SUSL}	$V_{IN} > V_{IL}$ (maximum)	22.5	—	25.0	—	30.0	—	50.0	—	70.0	—	µA
High sustaining current	I_{SUSH}	$V_{IN} < V_{IH}$ (minimum)	–22.5	—	–25.0	—	–30.0	—	–50.0	—	–70.0	—	µA
Low overdrive current	I_{ODL}	$0V < V_{IN} < V_{CCIO}$	—	120	—	160	—	200	—	300	—	500	µA
High overdrive current	I_{ODH}	$0V < V_{IN} < V_{CCIO}$	—	–120	—	–160	—	–200	—	–300	—	–500	µA
Bus-hold trip point	V_{TRIP}	—	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block.

Table 2-10: OCT Calibration Accuracy Specifications for Arria V GZ Devices

OCT calibration accuracy is valid at the time of calibration only.

I/O Standard	V_{CCIO} (V) (128)			V_{ID} (mV) (129)			$V_{ICM(DC)}$ (V)			V_{OD} (V) (130)			V_{OCM} (V) (130)		
	Min	Typ	Max	Min	Condition	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
RSDS (HIO) (133)	2.375	2.5	2.625	100	V_{CM} = 1.25 V	—	0.3	—	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini-LVDS (HIO) (134)	2.375	2.5	2.625	200	—	600	0.4	—	1.325	0.25	—	0.6	1	1.2	1.4
LVPECL (135), (136)	—	—	—	300	—	—	0.6	D_{MAX} ≤ 700 Mbps	1.8	—	—	—	—	—	—
	—	—	—	300	—	—	1	D_{MAX} > 700 Mbps	1.6	—	—	—	—	—	—

Related Information

Glossary on page 2-73

(128) Differential inputs are powered by VCCPD which requires 2.5 V.
(129) The minimum VID value is applicable over the entire common mode range, VCM.
(130) RL range: 90 ≤ RL ≤ 110 Ω.
(133) For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.
(134) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.
(135) LVPECL is only supported on dedicated clock input pins.
(136) For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Transmitter REFCLK Phase Noise (622 MHz) (141)	100 Hz	—	—	-70	—	—	-70	dBc/Hz
	1 kHz	—	—	-90	—	—	-90	dBc/Hz
	10 kHz	—	—	-100	—	—	-100	dBc/Hz
	100 kHz	—	—	-110	—	—	-110	dBc/Hz
	≥1 MHz	—	—	-120	—	—	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) (142)	10 kHz to 1.5 MHz (PCIe)	—	—	3	—	—	3	ps (rms)
R_{REF}	—	—	1800 ±1%	—	—	1800 ±1%	—	Ω

Related Information

Arria V Device Overview

For more information about device ordering codes.

Transceiver Clocks

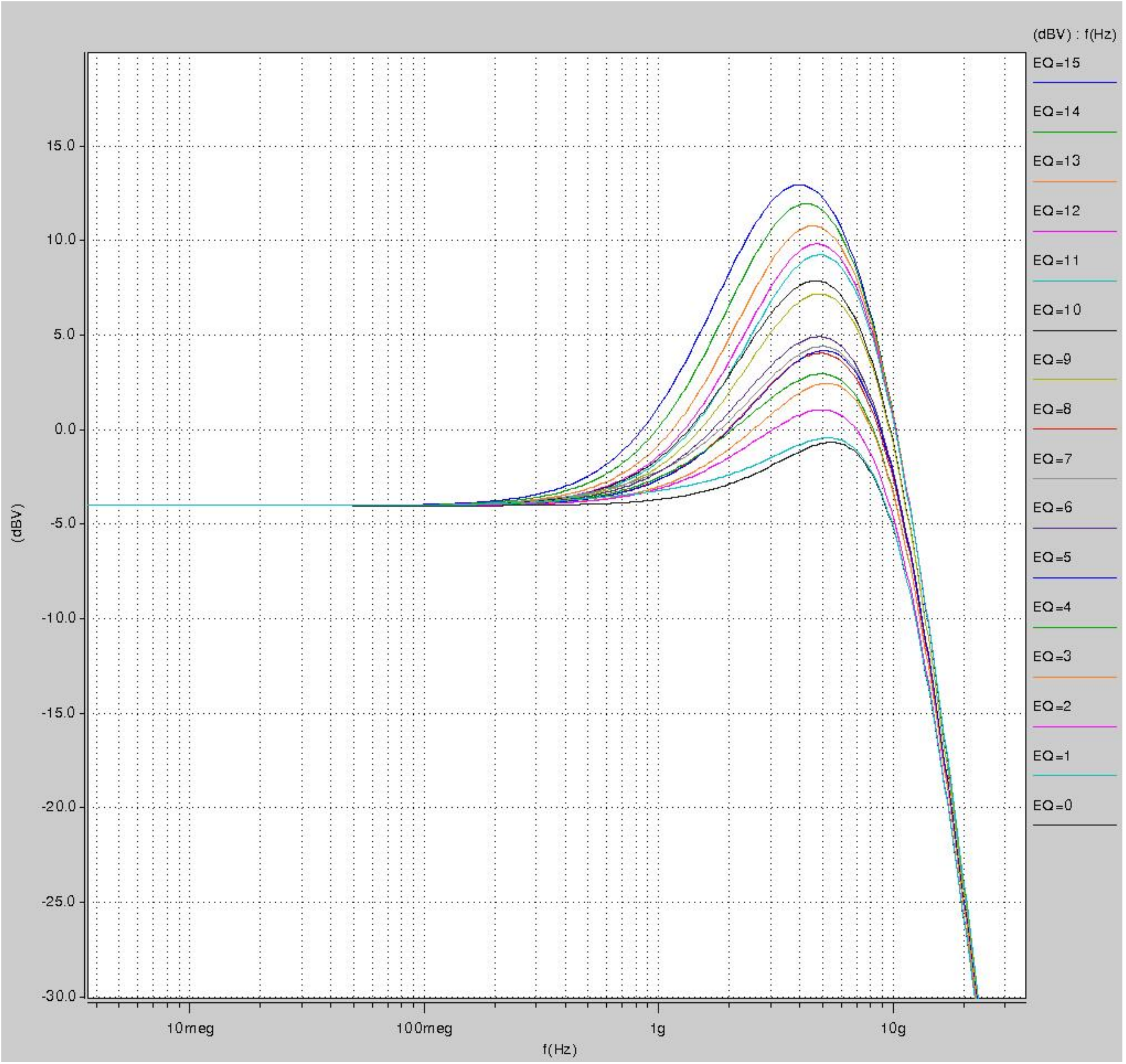
Table 2-23: Transceiver Clocks Specifications for Arria V GZ Devices

Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Arria V Device Overview*.

(141) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).

(142) To calculate the REFCLK rms phase jitter requirement for PCIe at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.

Figure 2-2: AC Gain Curves for Arria V GZ Channels (full bandwidth)



Symbol	Parameter	Min	Typ	Max	Unit
t_{INCCJ} (171), (172)	Input clock cycle-to-cycle jitter (f_{REF} ≥ 100 MHz)	—	—	0.15	UI (p-p)
	Input clock cycle-to-cycle jitter (f_{REF} < 100 MHz)	-750	—	+750	ps (p-p)
t_{OUTPJ_DC} (173)	Period Jitter for dedicated clock output in integer PLL (f_{OUT} ≥ 100 MHz)	—	—	175	ps (p-p)
	Period Jitter for dedicated clock output in integer PLL (f_{OUT} < 100 Mhz)	—	—	17.5	mUI (p-p)
t_{FOUTPJ_DC} (173)	Period Jitter for dedicated clock output in fractional PLL (f_{OUT} ≥ 100 MHz)	—	—	250(176), 175(174)	ps (p-p)
	Period Jitter for dedicated clock output in fractional PLL (f_{OUT} < 100 MHz)	—	—	25(176), 17.5 (174)	mUI (p-p)
t_{OUTCCJ_DC} (173)	Cycle-to-cycle Jitter for a dedicated clock output in integer PLL (f_{OUT} ≥ 100 MHz)	—	—	175	ps (p-p)
	Cycle-to-cycle Jitter for a dedicated clock output in integer PLL (f_{OUT} < 100 MHz)	—	—	17.5	mUI (p-p)
$t_{FOUTCCJ\_DC}$ (173)	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL (f_{OUT} ≥ 100 MHz)	—	—	250(176), 175 (174)	ps (p-p)
	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL (f_{OUT} < 100 MHz)	—	—	25(176), 17.5 (174)	mUI (p-p)

(171) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source with jitter < 120 ps.
(172) The f_{REF} is fIN/N specification applies when N = 1.
(173) Peak-to-peak jitter with a probability level of 10^{-12} (14 sigma, 99.99999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in the "Worst-Case DCD on Arria V GZ I/O Pins" table.
(174) This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.20–0.80 must be ≥ 1200 MHz.

Mode	Performance			Unit
	C3, I3L	C4	I4	
One sum of two 27 × 27	380	300	290	MHz
One sum of two 36 × 18	380	300		MHz
One complex 18 × 18	400	350		MHz
One 36 × 36	380	300		MHz
Modes using Three DSP Blocks				
One complex 18 × 25	340	275	265	MHz
Modes using Four DSP Blocks				
One complex 27 × 27	350	310		MHz

Memory Block Specifications

Table 2-36: Memory Block Performance Specifications for Arria V GZ Devices

To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50%** output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.

When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in F_{MAX}.

Memory	Mode	Resources Used		Performance				Unit
		ALUTs	Memory	C3	C4	I3L	I4	
MLAB	Single port, all supported widths	0	1	400	315	400	315	MHz
	Simple dual-port, x32/x64 depth	0	1	400	315	400	315	MHz
	Simple dual-port, x16 depth [178]	0	1	533	400	533	400	MHz
	ROM, all supported widths	0	1	500	450	500	450	MHz

(178) The F_{MAX} specification is only achievable with Fitter options, **MLAB Implementation In 16-Bit Deep Mode** enabled.

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
f_{HSCLK_in} (input clock frequency) True Differential I/O Standards [179]	Clock boost factor W = 1 to 40 [180]	5	—	625	5	—	525	MHz
f_{HSCLK_in} (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 [180]	5	—	625	5	—	525	MHz
f_{HSCLK_in} (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 [180]	5	—	420	5	—	420	MHz
f_{HSCLK_OUT} (output clock frequency)	—	5	—	625 [181]	5	—	525 [181]	MHz

Transmitter High-Speed I/O Specifications

Table 2-40: Transmitter High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

(179) This only applies to DPA and soft-CDR modes.
(180) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.
(181) This is achieved by using the LVDS clock network.

DPA Mode High-Speed I/O Specifications

Table 2-42: High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
DPA run length	—	—	—	10000	—	—	10000	UI

Figure 2-3: DPA Lock Time Specification with DPA PLL Calibration Enabled

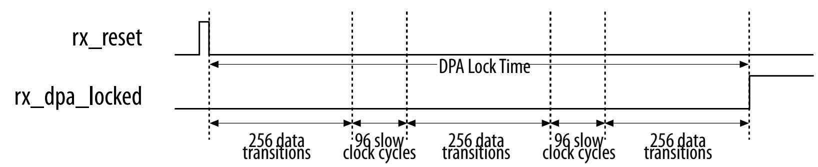


Table 2-43: DPA Lock Time Specifications for Arria V GZ Devices

The DPA lock time is for one channel.

One data transition is defined as a 0-to-1 or 1-to-0 transition.

The DPA lock time stated in this table applies to both commercial and industrial grade.

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions (201)	Maximum
SPI-4	00000000001111111111	2	128	640 data transitions

(201) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Note: When you enable the decompression or design security feature, the DCLK-to-DATA[] ratio varies for FPP ×8, FPP ×16, and FPP ×32. For the respective DCLK-to-DATA[] ratio, refer to the "DCLK-to-DATA[] Ratio for Arria V GZ Devices" table.

Table 2-56: FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is 1

Use these timing parameters when the decompression and design security features are disabled.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	µs
t_{STATUS}	nSTATUS low pulse width	268	1,506 [205]	µs
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 [206]	µs
t_{CF2CK} [207]	nCONFIG high to first rising edge on DCLK	1,506	—	µs
t_{ST2CK} [207]	nSTATUS high to first rising edge of DCLK	2	—	µs
t_{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency (FPP ×8/×16)	—	125	MHz
	DCLK frequency (FPP ×32)	—	100	MHz
t_{CD2UM}	CONF_DONE high to user mode [208]	175	437	µs

(205) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
(206) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.
(207) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

Table 2-62: Uncompressed .rbf Sizes for Arria V GZ Devices

Variant	Member Code	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) [223]
Arria V GZ	E1	137,598,880	562,208
	E3	137,598,880	562,208
	E5	213,798,880	561,760
	E7	213,798,880	561,760

Table 2-63: Minimum Configuration Time Estimation for Arria V GZ Devices

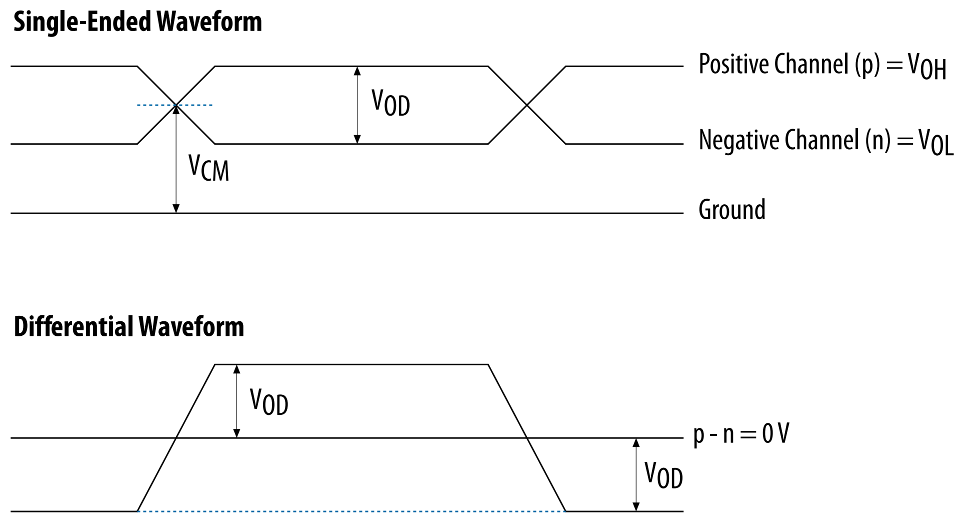
Variant	Member Code	Active Serial [224]			Fast Passive Parallel [225]		
		Width	DCLK (MHz)	Min Config Time (ms)	Width	DCLK (MHz)	Min Config Time (ms)
Arria V GZ	E1	4	100	344	32	100	43
	E3	4	100	344	32	100	43
	E5	4	100	534	32	100	67
	E7	4	100	534	32	100	67

Remote System Upgrades Circuitry Timing Specification

Table 2-64: Remote System Upgrade Circuitry Timing Specifications

Parameter	Minimum	Maximum	Unit
$t_{RU\_nCONFIG}$ [226]	250	—	ns
$t_{RU\_nRSTIMER}$ [227]	250	—	ns

(223) The IOCSR **.rbf** size is specifically for the Configuration via Protocol (CvP) feature.
(224) DCLK frequency of 100 MHz using external CLKUSR.
(225) Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

Term	Definition
	
f_{HSCLK}	Left and right PLL input clock frequency.
f_{HSDR}	High-speed I/O block—Maximum and minimum LVDS data transfer rate (f_{HSDR} = 1/TUI), non-DPA.
$f_{HSDRDPA}$	High-speed I/O block—Maximum and minimum LVDS data transfer rate ($f_{HSDRDPA}$ = 1/TUI), DPA.
J	High-speed I/O block—Deserialization factor (width of parallel data bus).

Term	Definition
t_C	High-speed receiver and transmitter input and output clock period.
TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the Timing Diagram figure under SW in this table).
t_{DUTY}	High-speed I/O block—Duty cycle on the high-speed transmitter output clock.
t_{FALL}	Signal high-to-low transition time (80-20%)
t_{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input.
t_{OUTPJ_IO}	Period jitter on the general purpose I/O driven by a PLL.
t_{OUTPJ_DC}	Period jitter on the dedicated clock output driven by a PLL.
t_{RISE}	Signal low-to-high transition time (20-80%)
Timing Unit Interval (TUI)	The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = 1/(receiver input clock frequency multiplication factor) = t_C/w)
$V_{CM(DC)}$	DC common mode input voltage.
V_{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.
V_{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
$V_{DIF(AC)}$	AC differential input voltage—Minimum AC input differential voltage required for switching.
$V_{DIF(DC)}$	DC differential input voltage— Minimum DC input differential voltage required for switching.
V_{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
$V_{IH(AC)}$	High-level AC input voltage
$V_{IH(DC)}$	High-level DC input voltage
V_{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
$V_{IL(AC)}$	Low-level AC input voltage
$V_{IL(DC)}$	Low-level DC input voltage